

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	23	(US-6165815-\$ or US-6265766-\$ or US-6222265-\$ or US-6157080-\$ or US-6365499-\$ or US-5241456-\$ or US-5111278-\$ or US-5355283-\$ or US-5081563-\$ or US-6340846-\$ or US-5715144-\$ or US-6451626-\$ or US-6051878-\$ or US-6706557-\$ or US-6429509-\$ or US-6117704-\$ or US-5861666-\$ or US-5353498-\$ or US-6486545-\$ or US-5399528-\$ or US-6451624-\$ or US-6153928-\$ or US-6489676-\$).did.	USPAT	OR	ON	2007/03/17 13:10
L2	2101	(circuit with (assembly or package)) and substrate and via and die and (ball or pin) and (fill or underfill or under-fill)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:18
L3	745	L2 and stacked	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:18
L4	452	L3 and dielectric	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:18
L5	83	L4 and stacked.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:18
L6	2542	257/676.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:32
L7	1917	257/700.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:40

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L8	2559	257/723.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:45
L9	1988	257/777.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:46
L10	0	((chip adj package) and (first with chip) and (second with chip) and (chip with (top adj surface)) and (first adj insulating adj layer) and (layer with sidewall) and (layer with top with chip) and (metal adj layer)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:48
S1	10	("5422435" "5608262" "5811351" "5952725" "5994166").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:29
S2	1564	(circuit with (assembly or package)) and substrate and via and die and (ball or pin) and (fill or underfill or under-fill)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 13:25
S3	556	S2 and stacked	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:55
S4	340	S3 and dielectric	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:39
S5	53	S4 and stacked.ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:17
S6	725	(circuit with (assembly or package)) and substrate and via and ((die or chip) with ((ball or pin) and (fill or underfill or under-fill)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 23:40
S7	226	S6 and stacked	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:55
S8	2	("6337227").URPN.	USPAT	OR	ON	2005/02/22 09:51

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S9	5	("5323060" "6337226" "6337227" "6340846" "6492726").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/22 09:52
S10	401	257/656.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 12:03
S11	1936	257/676.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/17 13:24
S12	6	"6613606"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 12:08
S13	8	("5422435" "5608262" "5811351" "5952725" "5994166" "6114187" "6228681" "6365499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 12:09
S14	25	("3339274" "3959874" "4172907" "4616406" "5120678" "5148266" "5155904" "5241133" "5316788" "5397917" "5433822" "5436203" "5468681" "5581122" "5663106" "5663593" "5798563" "5824569" "5889655" "6229209").PN. OR ("6365499").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 13:21
S15	11	S14 and planar\$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 13:21
S16	55	(circuit with (assembly or package)) and substrate and via and die and (ball or pin) and (fill or underfill or under-fill) and stacked and (dielectric with planar\$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 14:24
S17	1632	257/678.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 13:47
S18	434	257/752.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 13:50
S19	1357	257/700.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 14:10

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S20	1160	257/777.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 14:17
S21	1679	257/774.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 14:29
S22	1752	257/723.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 14:29
S23	7	(US-6051878-\$ or US-6157080-\$ or US-6165815-\$ or US-6222265-\$ or US-6265766-\$ or US-6340846-\$ or US-6365499-\$).did.	USPAT	OR	ON	2005/03/14 14:56
S24	33	("4954878" "5099306" "5109320" "5128831" "5222014" "5252857" "5291061" "5300801" "5323060" "5403784" "5422435" "5434745" "5466627" "5473814" "5477082" "5481134" "5494841" "5495398" "5496775" "5498902" "5498905" "5506756" "5508565" "5512765" "5512780" "5513076" "5535101" "5594275" "5639696" "5705858" "5715144" "5728606" "5729440").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 15:07
S25	30	("4446477" "5218234" "5222014" "5293068" "5434452" "5486723" "5952611" "6013946" "6048755" "6091140" "6097085").PN. OR ("6265766").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 15:50
S26	292	(circuit with (assembly or package)) and substrate and via and ((die or chip) with ((ball or pin) and (fill or underfill or under-fill))) and (planar\$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 16:11
S27	137	S26 and package.ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 16:11
S28	7	(US-6051878-\$ or US-6157080-\$ or US-6165815-\$ or US-6222265-\$ or US-6265766-\$ or US-6340846-\$ or US-6365499-\$).did.	USPAT	OR	ON	2005/12/21 14:20
S29	2009	((circuit or electronic) with (assembly or package)) and via and (chip or die) and (ball or bump) and (via with (insulation or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 15:22

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S30	135	S29 and stacked.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 14:27
S31	2	("5478781" "5952725").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/21 15:05
S32	64	S29 and (encapsulate with chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 15:21
S33	259	("5355283").URPN.	USPAT	OR	ON	2005/12/21 15:10
S34	415	S29 and (dielectric with (over and chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 15:21
S35	185	S34 and (stacked or layered)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 15:25
S36	74	S35 and ((stacked or layered) with (chip or die))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 15:25
S37	8	("5422435" "5608262" "5811351" "5952725" "5994166" "6114187" "6228681" "6365499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/21 15:39
S38	86	("5608262").URPN.	USPAT	OR	ON	2005/12/21 15:43
S39	1019	(semiconductor with package) and (second with chip) and (insulat\$3 with chip) and metal and via	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 17:00
S40	106	S39 and stacked.ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 14:56
S41	81	(semiconductor with package) and (second with chip) and (insulat\$3 with chip) and metal and via and (planar or co adj planar or coplanar) and stacked and wiring	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 17:22

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S42	424	(semiconductor with package) and (second with chip) and ((second or top) with chip) and metal and via and stacked and wiring	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 17:23
S43	94	S42 and ((second or top) with smaller)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 17:23
S44	5	("5726493" "6239496" "6303997" "6329915" "6348728").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/04 23:26
S45	985	Taniguchi.in. and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/04 23:30
S46	0	S45 and (electronic adj package)	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/04 23:30
S47	385	S45 and (electronic)	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/04 23:30
S48	23	(US-6051878-\$ or US-6340846-\$ or US-5715144-\$ or US-5241456-\$ or US-5355283-\$ or US-6706557-\$ or US-6265766-\$ or US-6451626-\$ or US-6365499-\$ or US-6222265-\$ or US-5081563-\$ or US-6165815-\$ or US-6157080-\$ or US-5111278-\$ or US-6429509-\$ or US-6117704-\$ or US-5861666-\$ or US-5353498-\$ or US-5399528-\$ or US-6486545-\$ or US-6153928-\$ or US-6451624-\$ or US-6489676-\$).did.	USPAT	OR	ON	2006/09/04 23:31
S49	704	((circuit or electronic) with (assembly or package)) and substrate and via and ((die or chip) with ((ball or pin) and (fill or underfill or under-fill))) and (second with (chip or die))	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:27
S50	55	S49 and (insulat\$4 or dielectric) and (wiring adj layer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 23:42
S51	259	S49 and stacked	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 23:56
S52	199	S51 and bump	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 23:57

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S53	4	("5594275" "5715144" "5751060" "5760478").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/05 00:04
S54	3168	((circuit or electronic) with (assembly or package)) and substrate and via and ((die or chip) with ((ball or pin))) and (second with (chip or die))	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:27
S55	619	S54 and (cover with chip)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:28
S56	581	S55 and (second with chip)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:28
S57	346	S56 and bump	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:28
S58	285	S57 and top	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:29
S59	102	S58 and stacked	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:46
S60	6	"6613606"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 00:46
S61	8	("5422435" "5608262" "5811351" "5952725" "5994166" "6114187" "6228681" "6365499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/05 00:46